

BRCO7330HME

CMOS

300mA

30V

CMOS

30V

B 300mA 2% 'ñ À-Àl ¯đMđ•@‡` l Á ý 8'4 Đô v

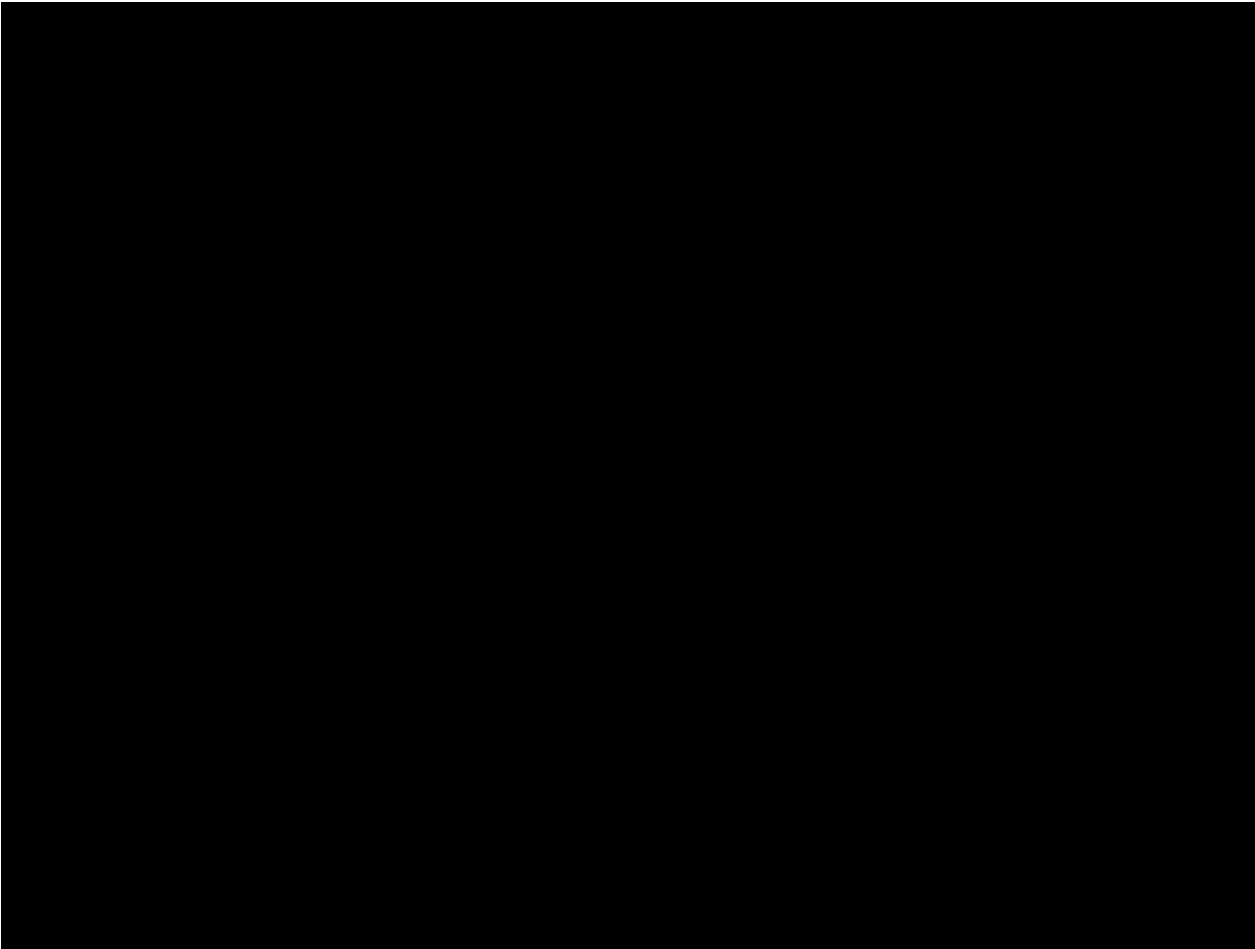
(M@E)A `(•Ù €Đ L I Á ý ß v iđ©p



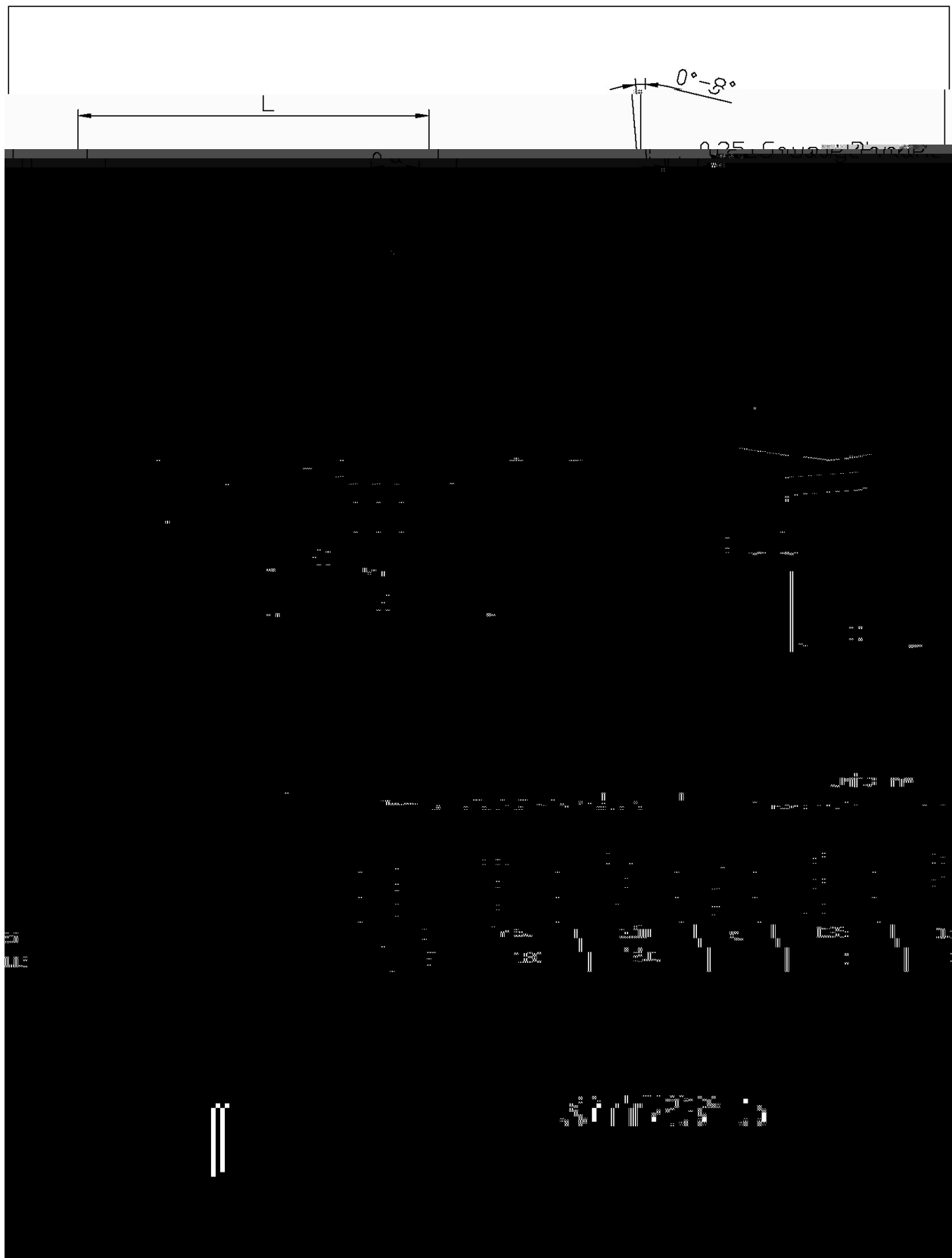
|    |               |                              |    |
|----|---------------|------------------------------|----|
|    |               |                              |    |
|    | $V_{IN\_MAX}$ | 30                           | V  |
|    | $V_{IN}$      | -0.3~30                      | V  |
| CE | $V_{CE}$      | $V_{IN}-0.3 \sim V_{IN}+0.3$ | V  |
|    | $I_{OUT}$     | 0~500                        | mA |
|    | $P_D$         | 0.3                          | W  |
|    | $T_{stg}$     | -40 to +150                  | °C |
|    | $T_{OP}$      | -40 to +85                   |    |

|  |             |                 |                       |     |                       |    |
|--|-------------|-----------------|-----------------------|-----|-----------------------|----|
|  |             |                 |                       |     |                       |    |
|  | $V_{IN}$    |                 | 2.5                   |     | 24                    | V  |
|  | $V_{OUT}$   | $I_{OUT}=10mA$  | $V_{OUT} \times 0.98$ |     | $V_{OUT} \times 1.02$ | V  |
|  | $I_{SS}$    | $I_{OUT}=0mA$   | -                     | 2.5 | 6                     | uA |
|  | $I_{ST}$    | CE=0V           |                       |     | 0.2                   | uA |
|  | $I_{LIM}$   | -               | 500                   |     |                       | mA |
|  | $V_{DROP}$  | $I_{OUT}=100mA$ | -                     | 200 | -                     | mV |
|  | $I_{SHORT}$ |                 |                       | 55  |                       | mA |
|  | $V_{CE\_L}$ |                 |                       |     | 0.4                   | V  |
|  | $V_{CE\_H}$ |                 | 1.5                   |     |                       | V  |

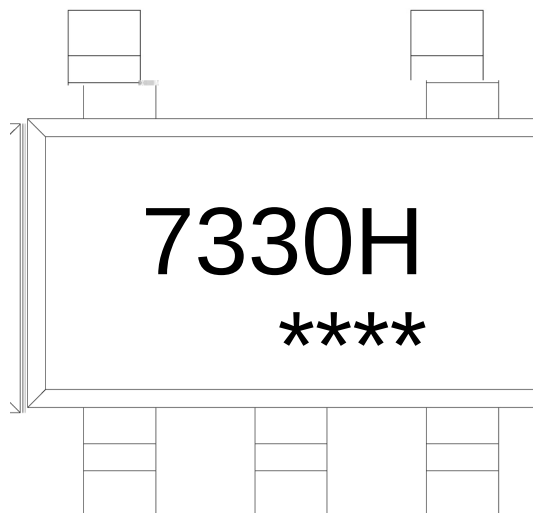
**/ Functionl Block Diagram**



/ Package Dimensions



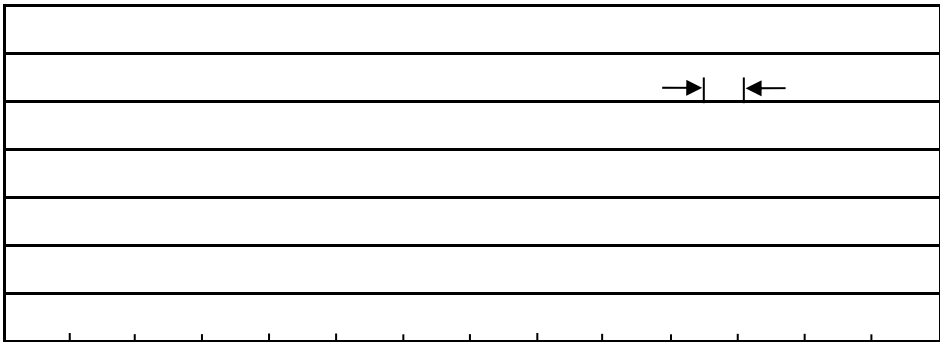
**/ Marking Instructions**



7330H

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(     ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



- Note:
- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.

2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3

2 10

/sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5                      10±1 sec.                      Temp.:260±5                      Time:10±1 sec

/ Packaging SPEC.

/ REEL

| Package Type | Units           |                      |                      |                            |                      | Dimension (unit mm <sup>3</sup> ) |             |             |
|--------------|-----------------|----------------------|----------------------|----------------------------|----------------------|-----------------------------------|-------------|-------------|
|              | Units/Reel<br>/ | Reels/Inner Box<br>/ | Units/Inner Box<br>/ | Inner Boxes/Outer Box<br>/ | Units/Outer Box<br>/ | Reel                              | Inner Box   | Outer Box   |
| SOT23-5/6    | 3,000           | 10                   | 30,000               | 4                          | 120,000              | 7 ×8                              | 210×205×205 | 445×435×230 |

/ Notices

All information provided in this document is subject to legal disclaimers.